

Line Number	Hits	Search Text	DB	Time stamp
1	14-1	"low-k" or dielectric or insulating and resist or photoresist or pattern or patterning or patterned and trench or via or contact or openings and etch\$3 and "dual damascene" or dual adj damascene	USPAT; EPO; JPO; IBM_TDB	2003/04/01 08:41
2	14-2	"low-k" or dielectric or insulating and resist or photoresist or pattern or patterning or patterned and trench or via or contact or openings and etch\$3 and "dual damascene" or dual adj damascene	USPAT; EPO; JPO; IBM_TDB	2003/04/01 08:41
3	14-3	"low-k" or dielectric or insulating and resist or photoresist or pattern or patterning or patterned and trench or via or contact or openings and etch\$3 and "dual damascene" or dual adj damascene	USPAT; EPO; JPO; IBM_TDB	2003/04/01 08:41
4	14-4	"low-k" or dielectric or insulating and resist or photoresist or pattern or patterning or patterned and trench or via or contact or openings and etch\$3 and "dual damascene" or dual adj damascene	USPAT; EPO; JPO; IBM_TDB	2003/04/01 08:41
5	14	"ash or ashing or ashed" and "in-situ" and etch\$3 and "low-k"	USPAT; EPO; JPO; IBM_TDB	2003/04/01 09:19
6	21	"low-k" or dielectric or insulating and resist or photoresist or pattern or patterning or patterned and trench or via or contact or openings and etch\$3 and "organosilicate glass" or OSG	USPAT; EPO; JPO; IBM_TDB	2003/04/01 09:14
7	231	"ash or ashing or ashed" same ("water vapor" or "H <sub>2</sub> sub.20") same oxygen or "O <sub>2</sub> sub.2"	USPAT; EPO; JPO; IBM_TDB	2003/04/01 09:33
8	24	"ash or ashing or ashed" same ("water vapor" or "H <sub>2</sub> sub.20") same oxygen or "O <sub>2</sub> sub.2" and ("low-k" or dielectric or insulating and resist or photoresist or pattern or patterning or patterned and trench or via or contact or openings and etch\$3	USPAT; EPO; JPO; IBM_TDB	2003/04/01 09:19
9	1	6390096.pn.	USPAT; EPO; JPO; IBM_TDB	2003/04/01 07:10
10	56	dielectric same ("organosilicate glass" or OSG or "black diamond")	USPAT; EPO; JPO; IBM_TDB	2003/04/01 08:18
11	76	dielectric and ("organosilicate glass" or OSG or "black diamond")	USPAT; EPO; JPO; IBM_TDB	2003/04/01 08:25
12	24	dielectric and ("organosilicate glass" or OSG)	USPAT; EPO; JPO; IBM_TDB	2003/04/01 08:47
13	173	"dielectric constant" and ("organosilicate glass" or OSG	USPAT; EPO; JPO; IBM_TDB	2003/04/01 09:17
14	3148	"low-k" or dielectric or insulating and resist or photoresist or pattern or patterning or patterned and trench or via or contact or openings and etch\$3 and ash or ashing or ashed	USPAT; EPO; JPO; IBM_TDB	2003/04/01 09:18
15	143	"low-k" or dielectric or insulating and resist or photoresist or pattern or patterning or patterned and trench or via or contact or openings and etch\$3 and ash or ashing or ashed and 43% f <sub>2</sub> o <sub>2</sub> and "water vapor" or "H <sub>2</sub> sub.20" and oxygen or "O <sub>2</sub> sub.2"	USPAT; EPO; JPO; IBM_TDB	2003/04/01 09:21
16	142	"low-k" or dielectric or insulating and resist or photoresist or pattern or patterning or patterned and trench or via or contact or openings and etch\$3 and ash or ashing or ashed and 43% f <sub>2</sub> o <sub>2</sub> and "water vapor" or "H <sub>2</sub> sub.20" and oxygen or "O <sub>2</sub> sub.2"	USPAT; EPO; JPO; IBM_TDB	2003/04/01 09:21